

# 2SB1264

## Silicon PNP Epitaxial Planar Type

For general amplification  
Complementary pair with 2SD622

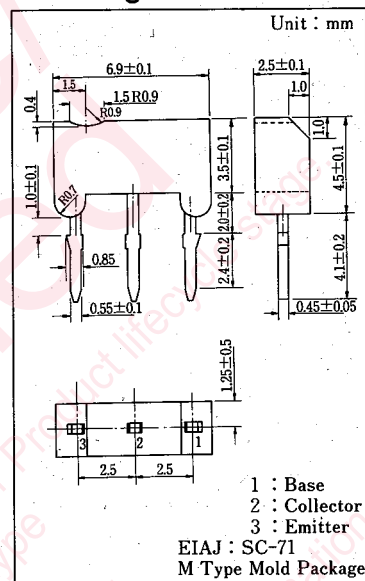
### ■ Features

- High collector-emitter voltage  $V_{CEO}$

### ■ Absolute Maximum Ratings ( $T_a=25^\circ\text{C}$ )

Item	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-250	V
Collector-Emitter Voltage	$V_{CEO}$	-200	V
Emitter-Base Voltage	$V_{EBO}$	-5	V
Peak Collector Current	$I_{CP}$	-100	mA
Collector Current	$I_C$	-70	mA
Collector Power Dissipation	$P_C$	600	mW
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 ~ +150	$^\circ\text{C}$

### ■ Package Dimensions

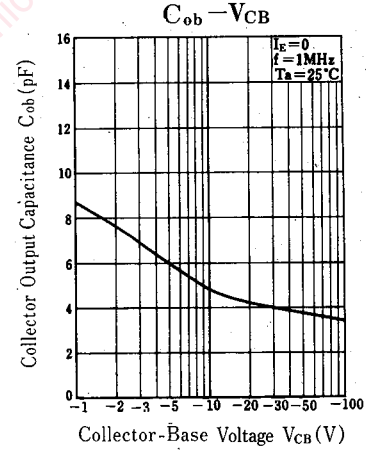
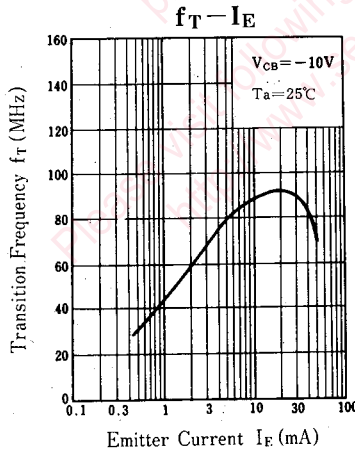
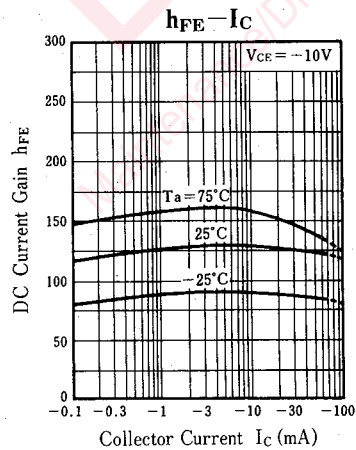
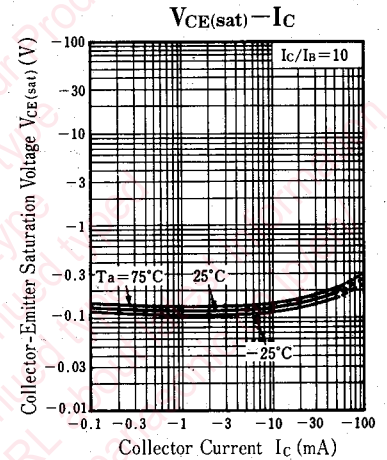
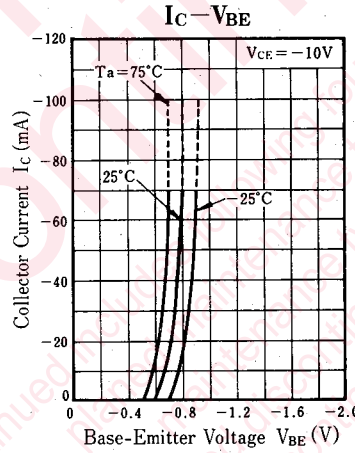
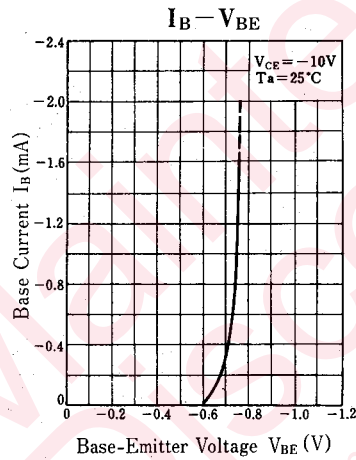
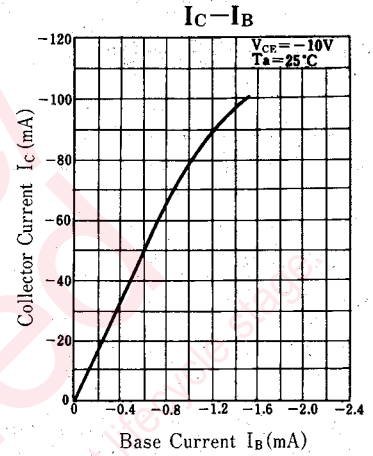
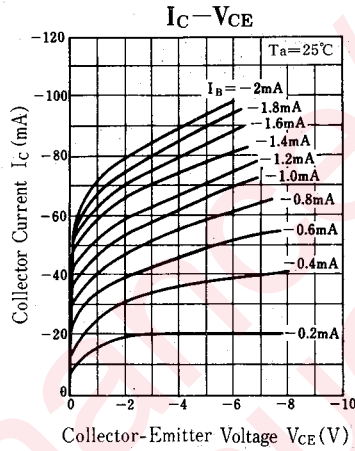
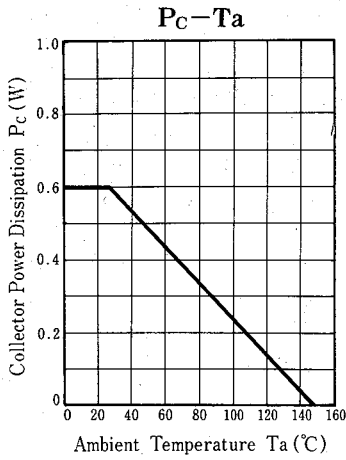


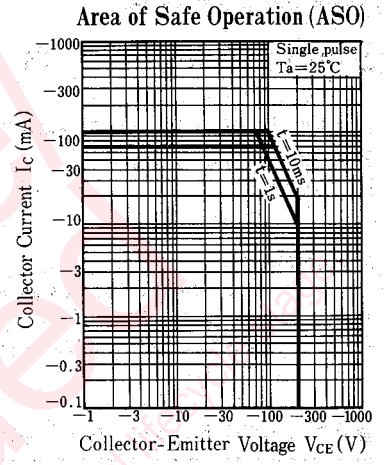
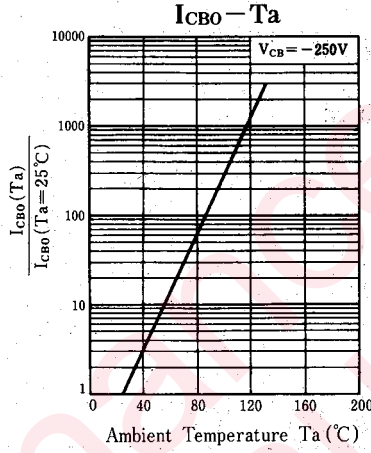
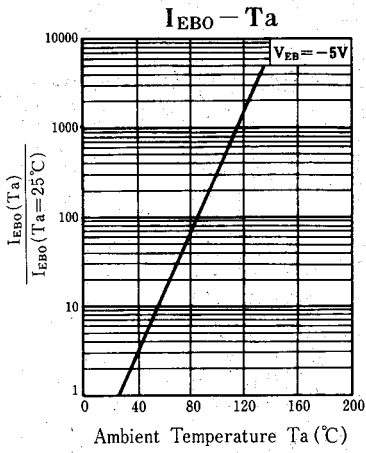
### ■ Electrical Characteristics ( $T_a=25^\circ\text{C}$ )

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector Cutoff Current	$I_{CEO}$	$V_{CE} = -120\text{V}, I_B = 0$			-1	$\mu\text{A}$
Collector-Emitter Voltage	$V_{CEO}$	$I_C = -100\ \mu\text{A}, I_B = 0$	-200			V
Emitter-Base Voltage	$V_{EBO}$	$I_E = -1\ \mu\text{A}, I_C = 0$	-5			V
DC Current Gain	$h_{FE}^*$	$V_{CE} = -10\text{V}, I_C = -5\ \text{mA}$	30		220	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -50\text{mA}, I_B = -5\ \text{mA}$			-1.5	V
Transition Frequency	$f_T$	$V_{CB} = -10\text{V}, I_E = 10\text{mA}, f = 200\text{MHz}$	50	80		MHz
Collector Output Capacitance	$C_{ob}$	$V_{CB} = -10\text{V}, I_E = 0, f = 1\ \text{MHz}$			10	pF

\*  $h_{FE}$  Ranking

Rank	P	Q	R
$h_{FE}$	30 ~ 100	60 ~ 150	100 ~ 220





Maintenance/Discontinued

includes following four Product

planned maintenance type

planned discontinued type

discontinued type

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